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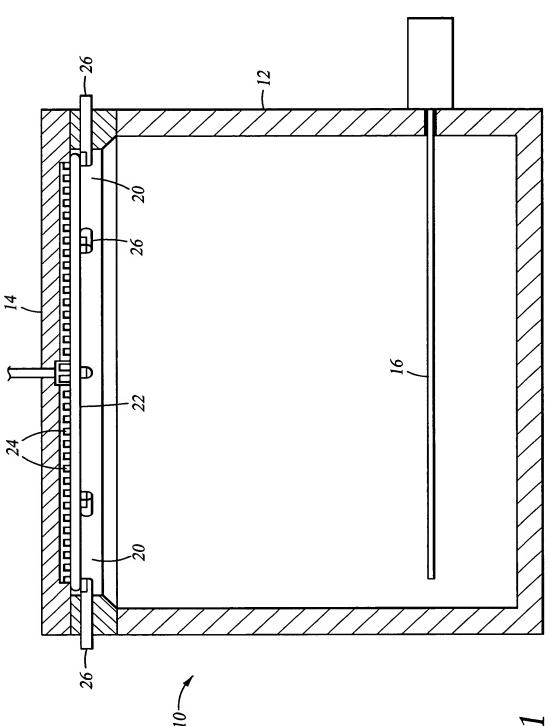
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COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING

INVENTOR: CHEUNG, ET AL.

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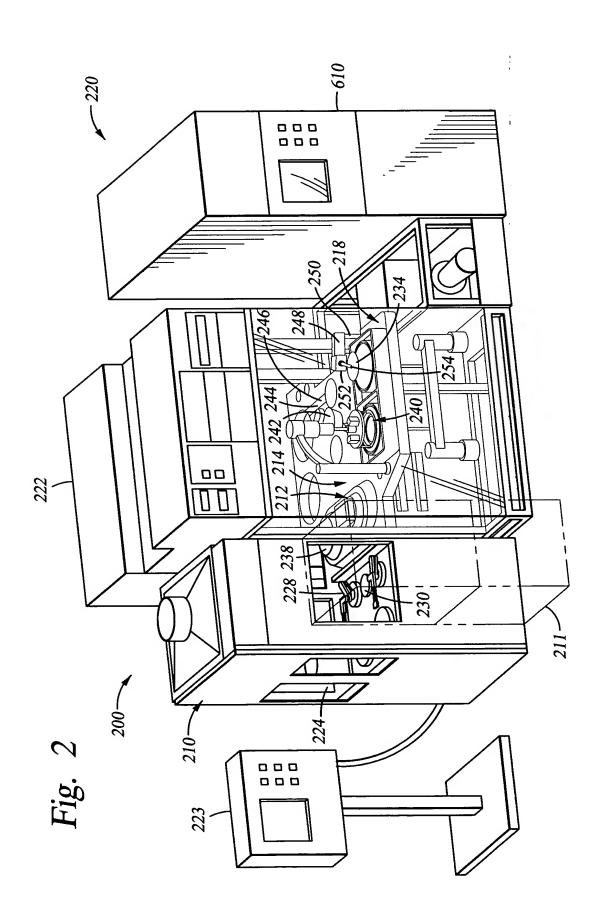
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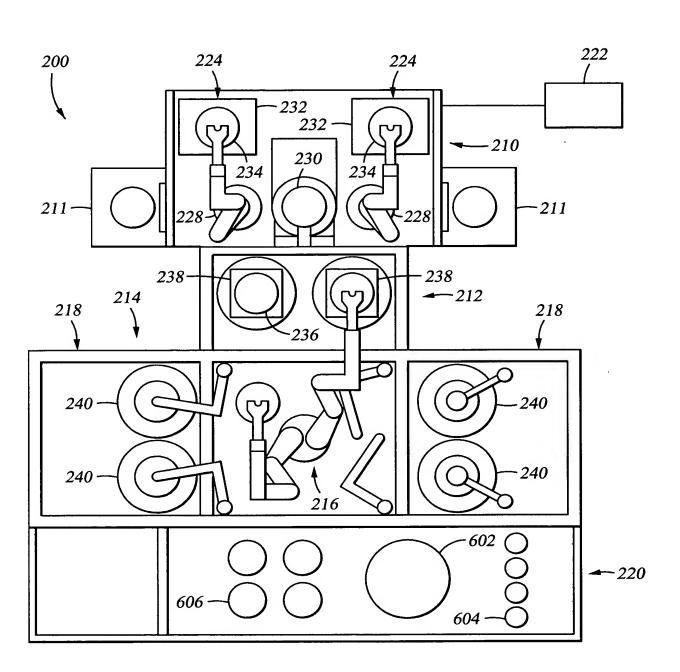


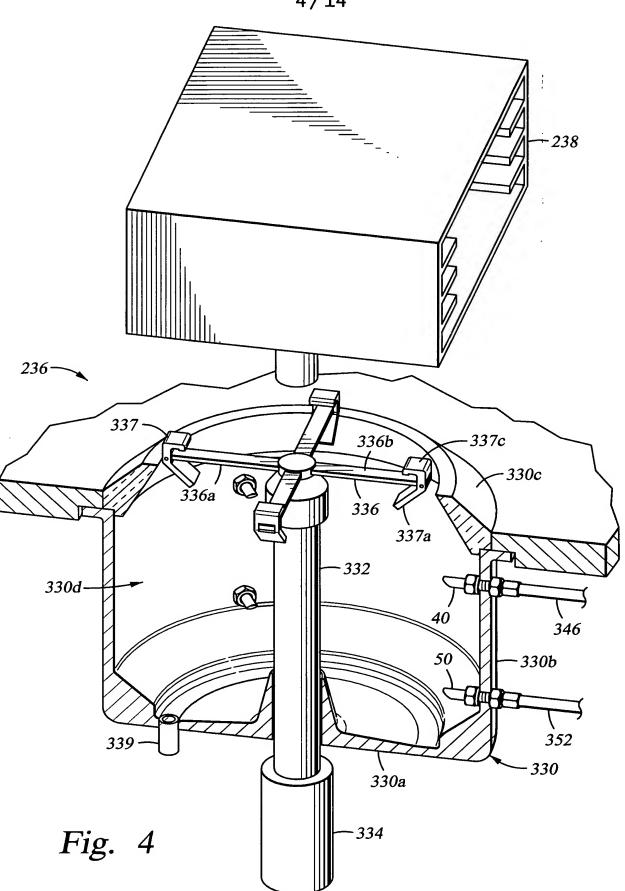
Fig. 3

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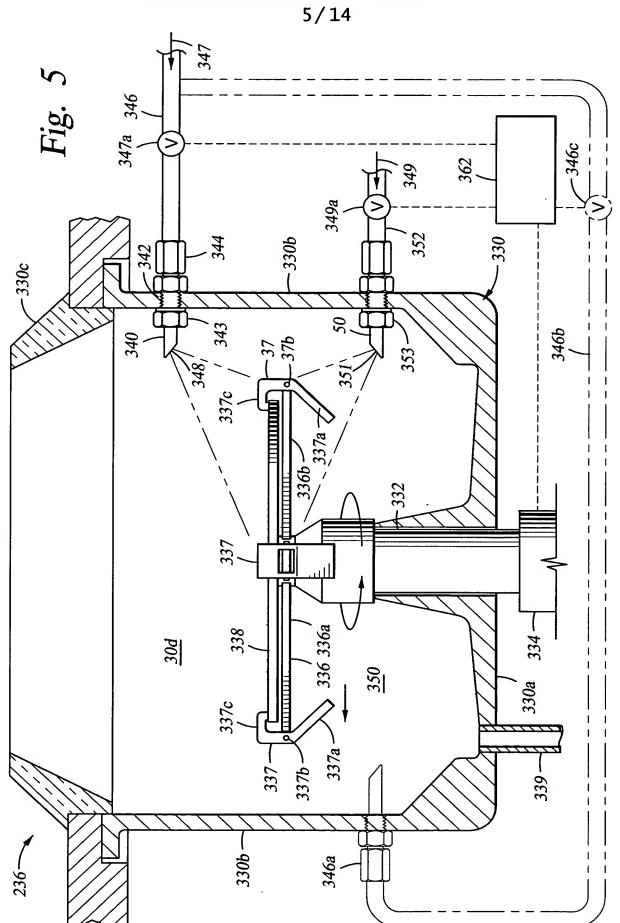
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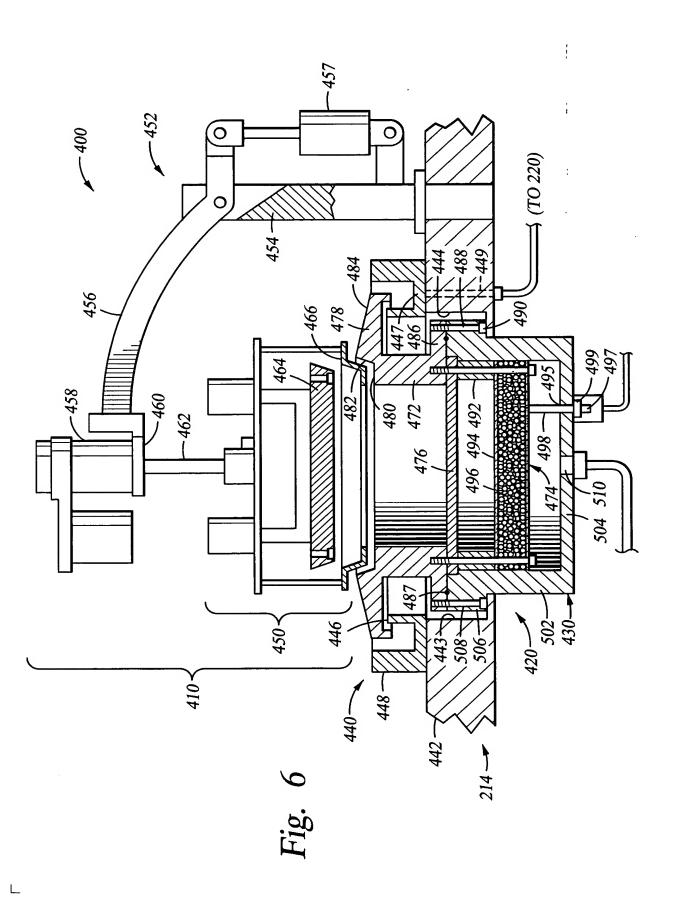


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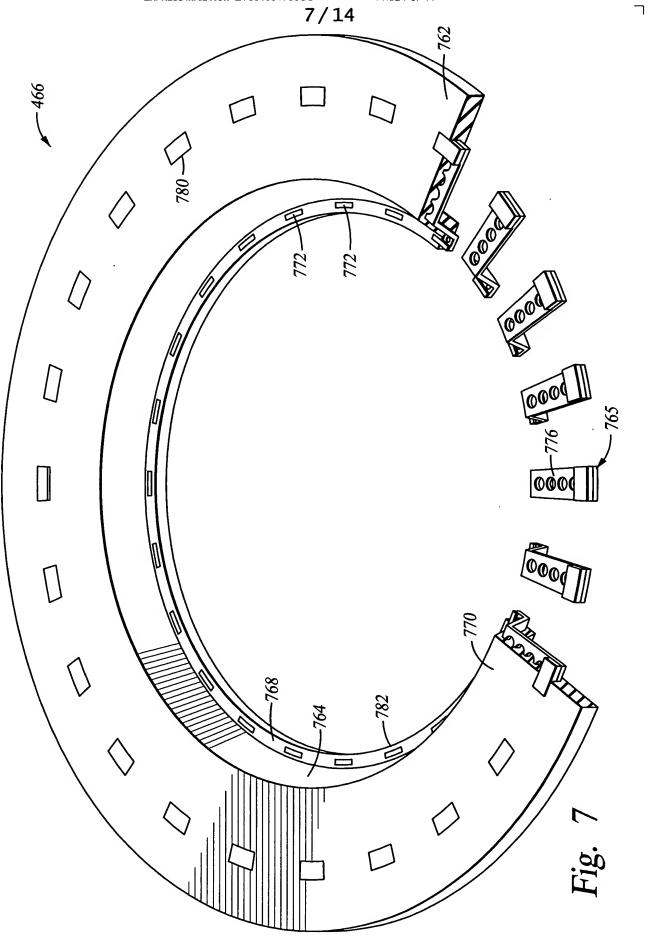
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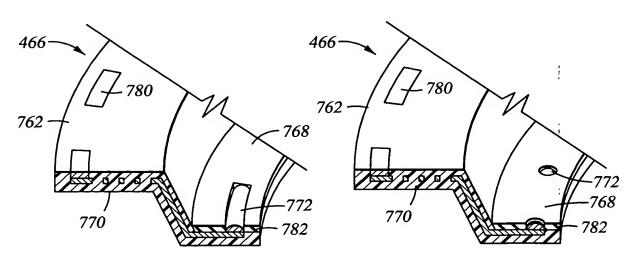
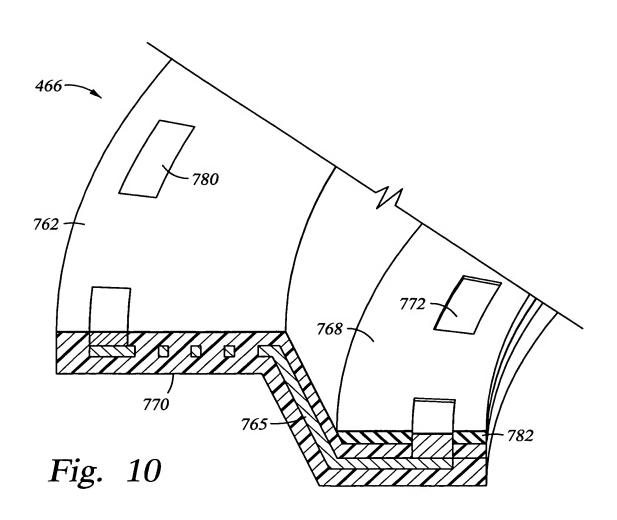


Fig. 8

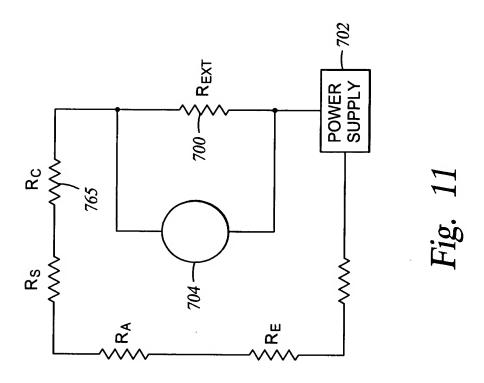
Fig. 9

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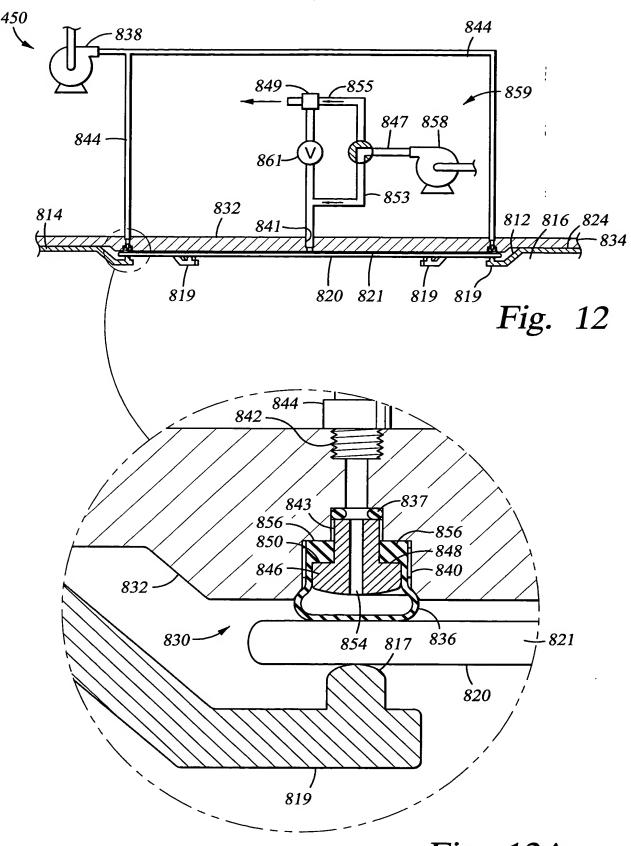
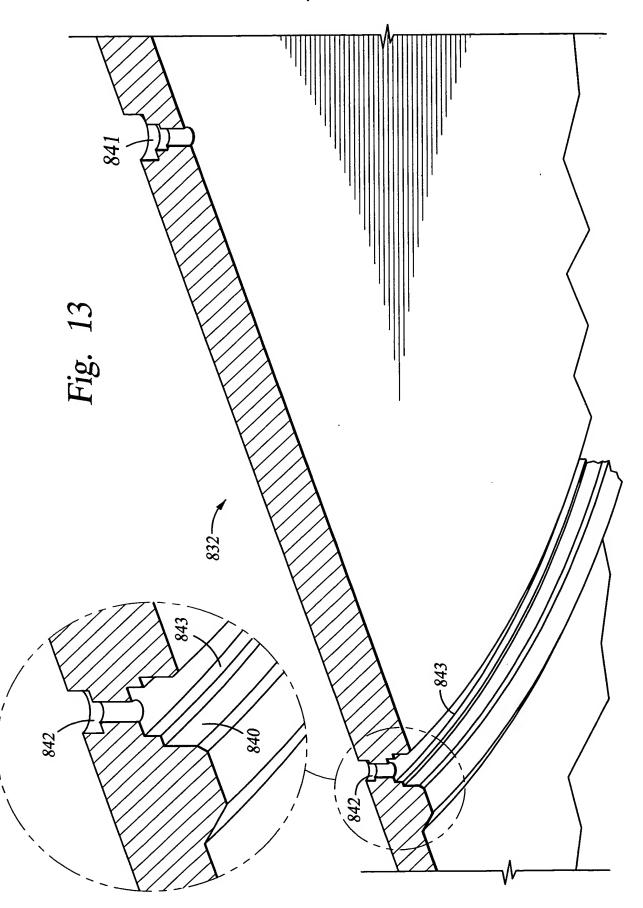


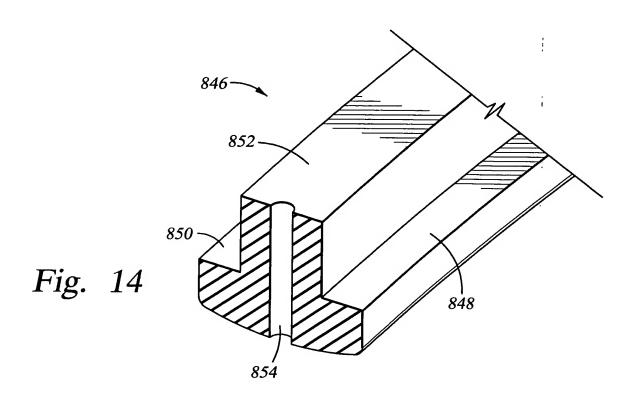
Fig. 12A

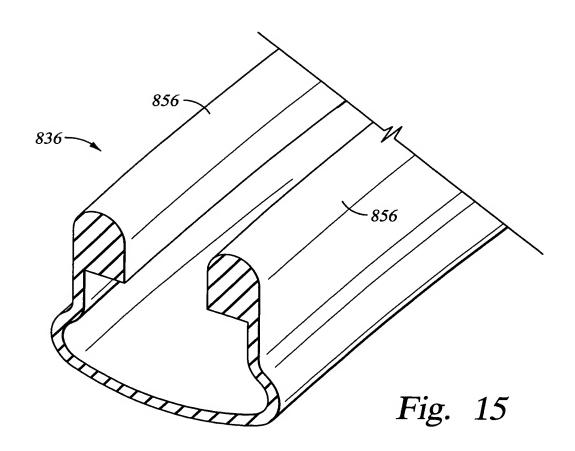
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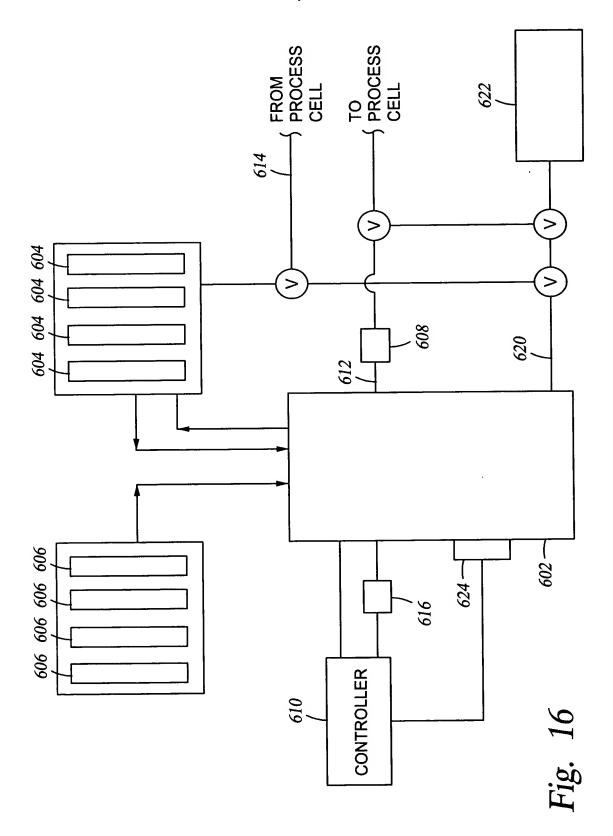
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